



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSB104N08NP3 G	<b>Issued</b>	24. February 2022
<b>MA#</b>	MA005708717		
<b>Package</b>	MG-WDSO-2-6	<b>Weight*</b>	79.78 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.759	3.46	3.46	34582	34582
leadframe	non noble metal	copper	7440-50-8	74.415	93.29	93.29	932805	932805
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.26		2647	
	noble metal	silver	7440-22-4	0.840	1.05	1.31	10530	13177
plating	non noble metal	nickel	7440-02-0	0.211	0.26	0.26	2647	2647
glue	miscellaneous	miscellaneous	-	0.017	0.02		216	
	plastics	acrylic resin	-	0.135	0.17		1687	
	noble metal	silver	7440-22-4	0.860	1.08	1.27	10782	12685
passivation	plastics	epoxy resin	-	0.327	0.41	0.41	4104	4104
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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